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(57)

**ABSTRACT**

An electronic device is provided and includes a circuit board and a casing. The circuit board includes a plate body, a perforation and a ground wire. The perforation penetrates through the plate body, the ground wire is electrically coupled with the plate body and crosses over the perforation. The casing includes a bottom plate and a clamping structure. The clamping structure is disposed on the bottom plate and includes a first clamping part and a second clamping part. The circuit board is disposed in the casing, and the clamping structure penetrates through the plate body through the perforation, so that the circuit board is positioned on the casing, and the ground wire is clamped by the first clamping part and the second clamping part of the clamping structure. Consequently, the circuit board is grounded with the casing.

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